

Amendments to the Claims:

Please amend the claims as shown below.

Listing of Claims:

This listing of the pending claims is provided for the Examiner's convenience.

Claims 1-43 (Canceled)

44. (Currently Amended) A circuit component comprising:

a substrate;

a semiconductor chip over a top surface of said substrate, wherein said semiconductor chip has a front surface facing said top surface of said substrate and a back surface opposite said front surface, wherein said semiconductor chip comprises multiple pads at said front surface;

an identity of product directly on said back surface of said semiconductor chip;

multiple metal bumps between said multiple pads of said semiconductor chip and said top surface of said substrate; and

an optically transparent colored encapsulation layer vertically over said identity of product, wherein said identity of product is readable ~~visible~~ through said optically transparent colored encapsulation layer as laser radiation is directed through said optically transparent colored encapsulation layer upon said identity of product.

Claims 45-47 (Canceled)

48. (Previously Presented) The circuit component of claim 44 further comprising an underfill between said front surface and said top surface, wherein said underfill contacts said front surface and said top surface, wherein said multiple metal bumps are in said underfill.

49. (Previously Presented) The circuit component of claim 44 further comprising multiple balls on a bottom surface of said substrate.

Claims 50-59 (Canceled)

60. (Previously Presented) The circuit component of claim 44, wherein said multiple metal bumps comprise a solder.

61. (Currently Amended) A circuit component comprising:

a substrate;

a semiconductor chip over a top surface of said substrate, wherein said semiconductor chip has a front surface facing said top surface of said substrate and a back surface opposite said front surface, wherein said semiconductor chip comprises multiple pads at said front surface;

an identity of manufacturer directly on said back surface of said semiconductor chip;

multiple metal bumps between said multiple pads of said semiconductor chip and said top surface of said substrate; and

an optically transparent colored encapsulation layer vertically over said identity of manufacturer, wherein said identity of manufacturer is readable ~~visible~~ through said optically transparent colored encapsulation layer as laser radiation is directed through said optically transparent colored encapsulation layer upon said identity of product.

62. (Previously Presented) The circuit component of claim 61 further comprising an underfill between said front surface and said top surface of said substrate, wherein said underfill contacts said front surface and said top surface, wherein said multiple metal bumps are in said underfill.

63. (Previously Presented) The circuit component of claim 61 further comprising multiple balls on a bottom surface of said substrate.

64. (Previously Presented) The circuit component of claim 61, wherein said multiple metal bumps comprise a solder.

65. (Currently Amended) A circuit component comprising:

a substrate;

a semiconductor chip over a top surface of said substrate, wherein said semiconductor chip has a front surface facing said top surface of said substrate and a back surface opposite said front surface, wherein said semiconductor chip comprises multiple pads at said front surface;

a bar code directly on said back surface of said semiconductor chip;
multiple metal bumps between said multiple pads of said semiconductor chip and said top surface of said substrate; and
an optically transparent colored encapsulation layer vertically over said bar code, wherein said bar code is readable ~~visible~~ through said optically transparent colored encapsulation layer as laser radiation is directed through said optically transparent colored encapsulation layer upon said identity of product.

66. (Previously Presented) The circuit component of claim 65 further comprising an underfill between said front surface and said top surface, wherein said underfill contacts said front surface and said top surface, wherein said multiple metal bumps are in said underfill.

67. (Previously Presented) The circuit component of claim 65 further comprising multiple balls on a bottom surface of said substrate.

68. (Previously Presented) The circuit component of claim 65, wherein said multiple metal bumps comprise a solder.